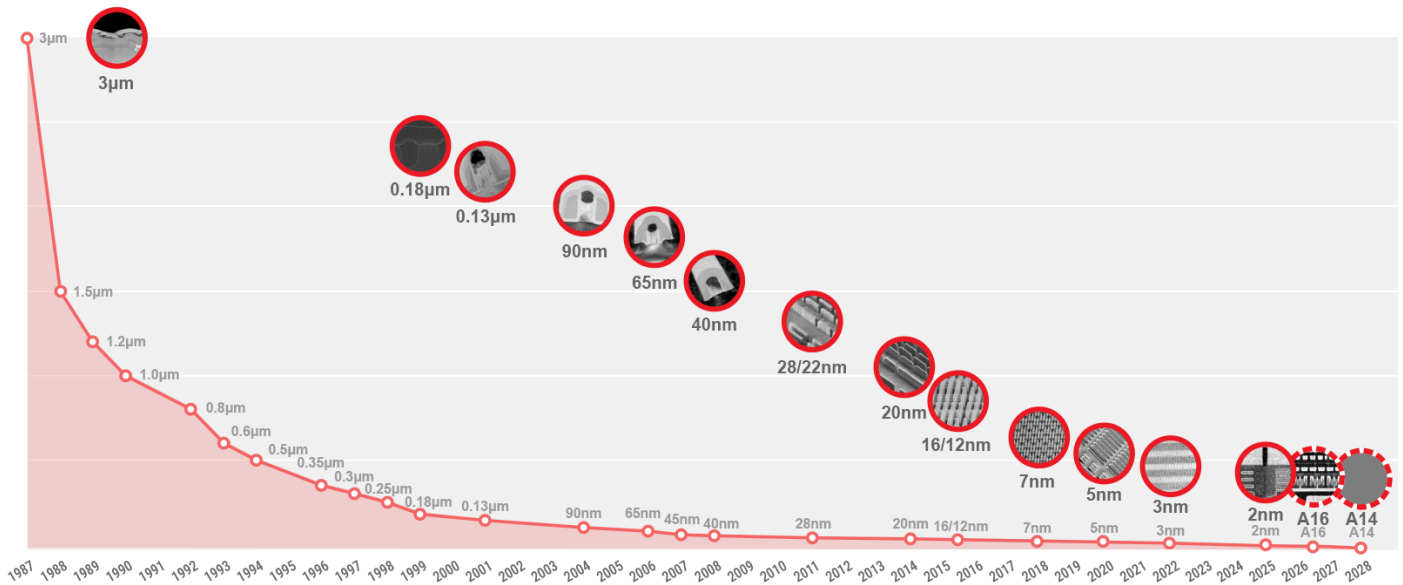


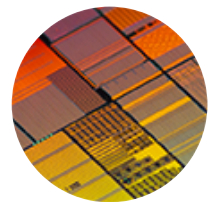
# 16/12nm Technology

TSMC has always insisted on building a strong, in-house R&D capability. As a global semiconductor technology leader, TSMC provides the most advanced and comprehensive portfolio of dedicated foundry process technologies.



## A14 Technology

A14 technology is TSMC's next cutting-edge logic process that achieves full-node power, performance and area through dimensional scaling. A14 is designed to drive AI transformation forward by delivering...



## A16 Technology

TSMC A16™ technology integrates leading nanosheet transistors with innovative Super Power Rail (SPR) solutions, bringing greatly improved logic density and performance. SPR improves logic density and...



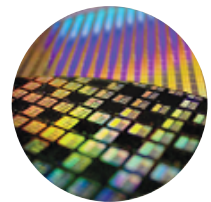
## 2nm Technology

TSMC's 2nm (N2) technology has started volume production in 4Q25 as planned. N2 technology features first-generation nanosheet transistor technology, with full-node strides in performance and power consumption...



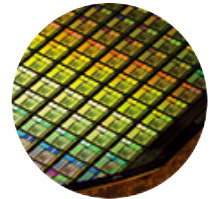
## 3nm Technology

In 2022, TSMC became the first foundry to move 3nm FinFET (N3) technology into high-volume production. N3 technology is the industry's most advanced process technology, offering the best...



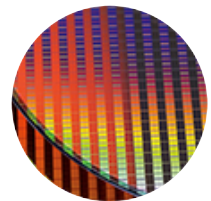
## 5nm Technology

In 2020, TSMC became the first foundry to move 5nm FinFET (N5) technology into volume production and enabled customers' innovations in smartphone and high-performance computing (HPC) applications...



## 7nm Technology

In 2018, TSMC became the first foundry to start 7nm FinFET (N7) volume production. The N7 technology is one of TSMC's fastest technologies to reach volume production and provides optimized manufacturing...



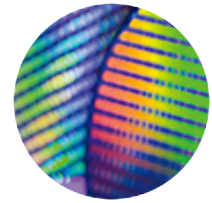
## 16/12nm Technology

In 2013, TSMC became the first foundry to begin 16nm Fin Field Effect Transistor (FinFET) technology risk production and later in 2014, the first foundry to deliver



## 20nm Technology

TSMC became the world's first semiconductor company that began 20nm volume production, using its innovative double patterning...

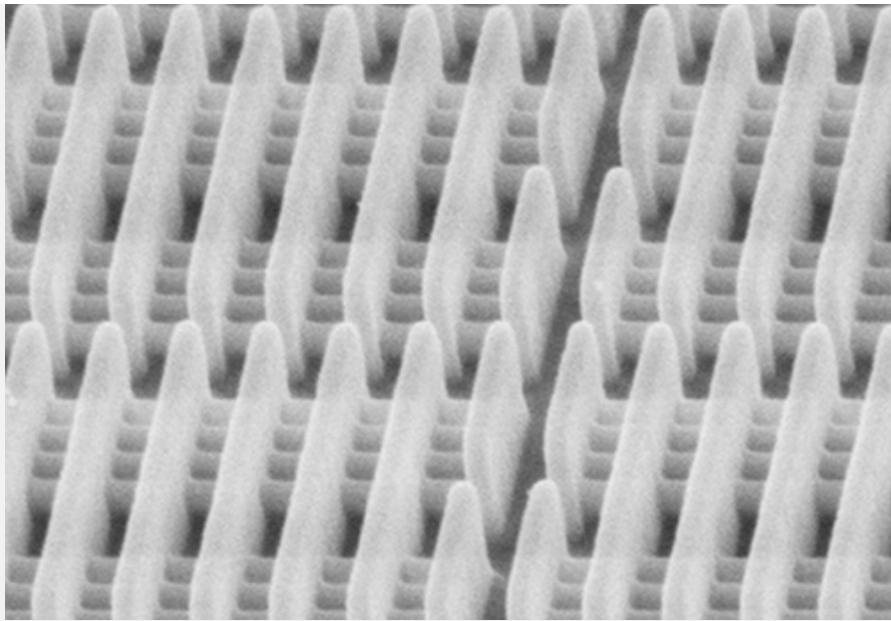


In 2013, TSMC became the first foundry to begin 16nm Fin Field Effect Transistor (FinFET) technology risk production and later in 2014, the first foundry to deliver a fully functional 16nm FinFET customer networking processor.

TSMC also introduced a more cost-effective 16nm FinFET Compact (16FFC) technology, which entered production in 2016. This process maximizes die cost scaling by simultaneously incorporating optical shrink and process simplification. The 12nm FinFET Compact Plus (12FFC+) technology further enhances gate density, speed, and power and entered production in 2017. It serves as the foundation for the N12e<sup>®</sup> technology platform, offering ultra-low leakage devices, low v<sub>dd</sub> solutions, RF models, analog enhancements, and eNVM (magnetoresistive random access memory, MRAM/ resistive random-access memory, RRAM).

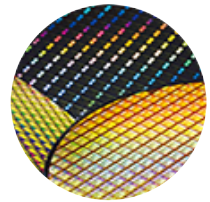
TSMC's 16/12nm processes provide the best performance among the industry's 16/14nm offerings. It is 50% faster and consumes 60% less power at the same speed, compared to TSMC's 20nm SoC process. TSMC's 16/12nm processes provide superior performance and power consumption advantage for next-generation high-end mobile computing, edge artificial intelligent Internet of Things (including microcontroller unit, MCUs, wearables, high speed interface products, vision AI, voice AI, ultra-low power products, memory controllers, and healthcare applications, etc.), digital consumer, and automotive electronic product applications.





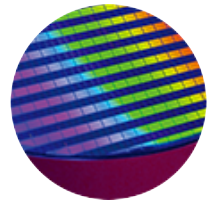
## 22nm Technology

The 22nm Ultra-Low Power (22ULP) process technology is derived from TSMC's industry-leading 28nm technology. It delivers enhanced performance and cost efficiency, making it suitable for...



## 28nm Technology

In 2011, TSMC became the first foundry that provided 28nm General Purpose process technology. Following this, TSMC continued to...



## 40nm Technology

TSMC led the foundry segment to start the volume production of a variety of products for multiple customers...



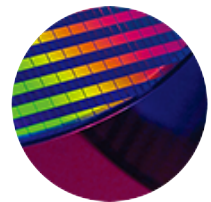
## 65nm Technology

TSMC became the first foundry to begin 65nm risk production in 2005 and passed product certification the following year...



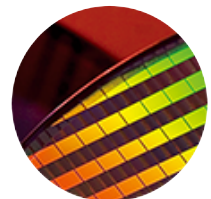
## 90nm Technology

TSMC became the first semiconductor company to produce fully-functional 90nm chips using immersion lithography technology...



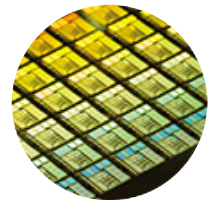
## 0.13 $\mu$ m Technology

TSMC launched the semiconductor industry's first 0.13 $\mu$ m low-k, copper system-on-a-chip (SoC) process technology...



## 0.18 $\mu$ m Technology

TSMC's 0.18 $\mu$ m logic technology marked a significant milestone in semiconductor manufacturing and today provides a reliable and proven solution for a wide range of applications. This mature process node...



## 3 $\mu$ m Technology



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